

MOS FIELD EFFECT TRANSISTOR 2SK3634

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3634 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, and designed for high voltage applications such as DC/DC converter.

★ ORDERING INFORMATION

PART NUMBER	PACKAGE		
2SK3634	TO-251 (MP-3)		
2SK3634-Z	TO-252 (MP-3Z)		

FEATURES

- High voltage: VDSS = 200 V
- Gate voltage rating: ±30 V

 $R_{DS(on)} = 0.60 \Omega MAX. (V_{GS} = 10 V, I_{D} = 3.0 A)$

- Low Ciss: Ciss = 270 pF TYP. (VDS = 10 V, VGS = 0 V)
- · Built-in gate protection diode
- TO-251/TO-252 package
- · Avalanche capability rated

(TO-251)



ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C)

Drain to Source Voltage (Vgs = 0 V)	Voss	200	V
Gate to Source Voltage (V _{DS} = 0 V)	Vgss	±30	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±6.0	Α
Drain Current (Pulse) Note1	ID(pulse)	±18	Α
Total Power Dissipation (Tc = 25°C)	P _{T1}	20	W
Total Power Dissipation (T _A = 25°C)	P _{T2}	1.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C
Single Avalanche Current Note2	las	6.0	Α
Single Avalanche Energy Note2	Eas	3.6	mJ
Repetitive Avalanche Current Note3	I AR	6.0	Α
Repetitive Pulse Avalanche Energy Note3	Ear	2.0	mJ

(TO-252)



- **Notes 1.** PW \leq 10 μ s, Duty Cycle \leq 1%
 - 2. Starting Tch = 25°C, VdD = 100 V, Rg = 25 Ω , Vgs = 20 \rightarrow 0 V, L = 100 μ H
 - 3. $T_{ch} \le 125^{\circ}C$, RG = 25 Ω , VDD = 100 V

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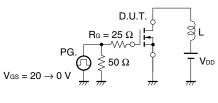
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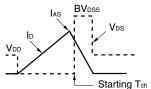


ELECTRICAL CHARACTERISTICS (TA = 25°C)

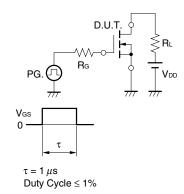
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 200 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	V _{GS} = ±30 V, V _{DS} = 0 V			±10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	2.5	3.5	4.5	V
Forward Transfer Admittance	y fs	V _{DS} = 10 V, I _D = 3.0 A	2	4		S
Drain to Source On-state Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 3.0 A		0.47	0.60	Ω
Input Capacitance	Ciss	V _{DS} = 10 V		270		pF
Output Capacitance	Coss	V _{GS} = 0 V		75		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		33		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 100 V, I _D = 3.0 A		4		ns
Rise Time	tr	V _{GS} = 10 V		8		ns
Turn-off Delay Time	t d(off)	$R_G = 0 \Omega$		14		ns
Fall Time	t _f			6		ns
Total Gate Charge	QG	V _{DD} = 160 V		9		nC
Gate to Source Charge	Qgs	V _{GS} = 10 V		1.5		nC
Gate to Drain Charge	Q _{GD}	I _D = 6.0 A		4.5		nC
Body Diode Forward Voltage	V _{F(S-D)}	I _F = 16 A, V _{GS} = 0 V		1.0		V
Reverse Recovery Time	trr	I _F = 6 A, V _{GS} = 0 V		100		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		320		nC

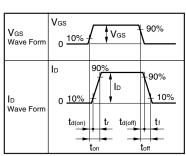
TEST CIRCUIT 1 AVALANCHE CAPABILITY



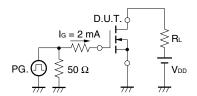


TEST CIRCUIT 2 SWITCHING TIME



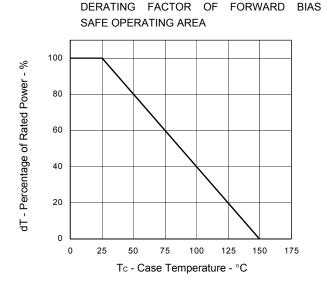


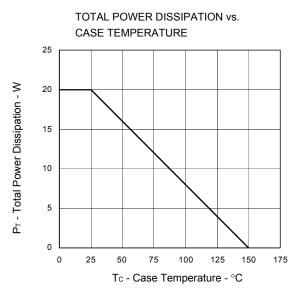
TEST CIRCUIT 3 GATE CHARGE



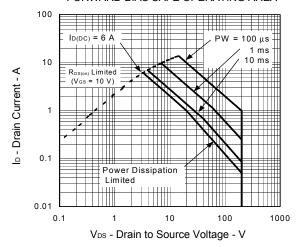


TYPICAL CHARACTERISTICS (TA = 25°C)

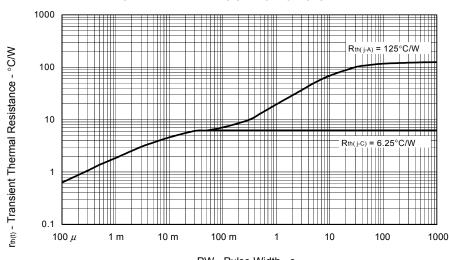




FORWARD BIAS SAFE OPERATING AREA

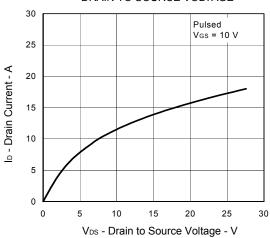


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

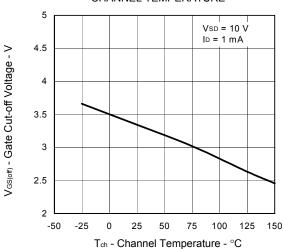


PW - Pulse Width - s

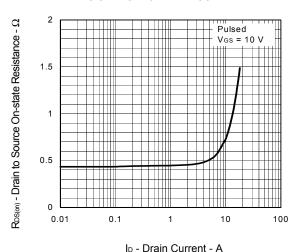
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



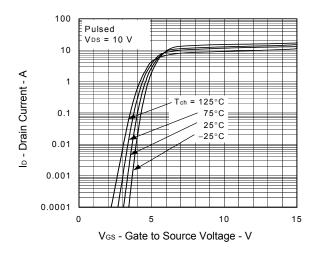
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



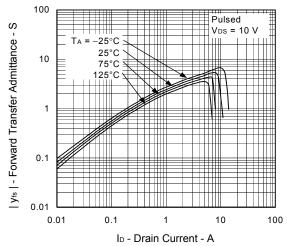
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



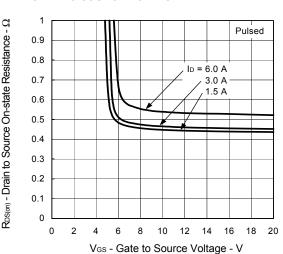
FORWARD TRANSFER CHARACTERISTICS



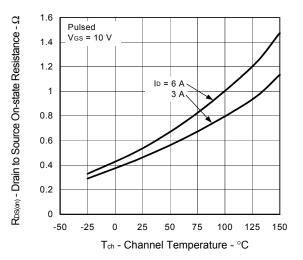
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



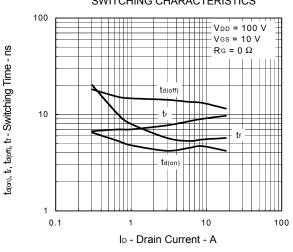
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



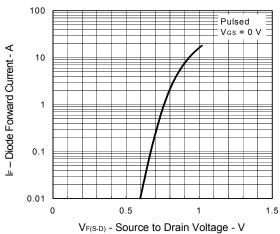
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



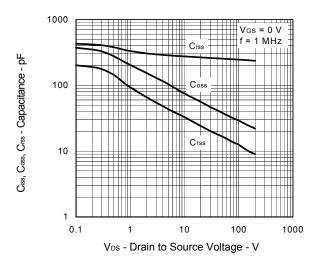
SWITCHING CHARACTERISTICS



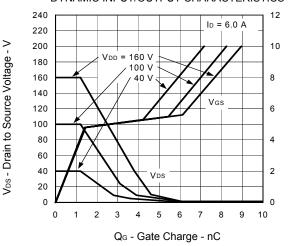
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



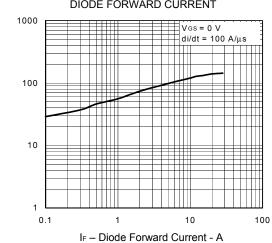
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



DYNAMIC INPUT/OUTPUT CHARACTERISTICS



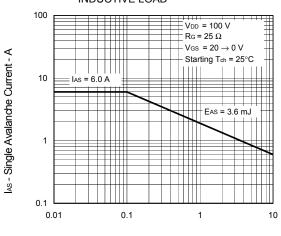
REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



Ves - Gate to Drain Voltage - V

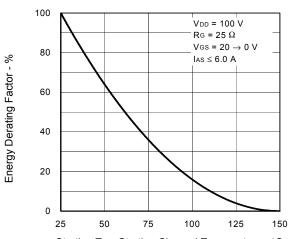
tr - Reverse Recovery Time - ns

SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



L - Inductive Load - mH

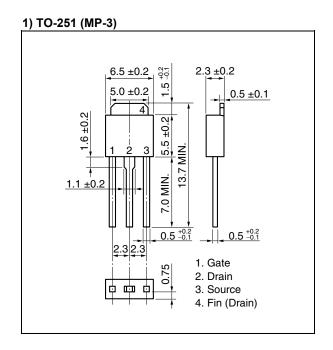
SINGLE AVALANCHE ENERGY DERATING FACTOR

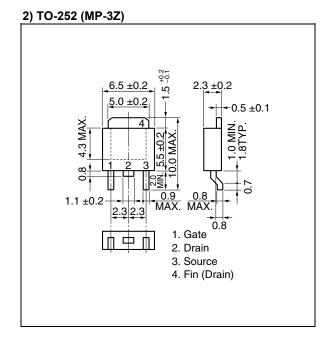


Starting Tch - Starting Channel Temperature - °C

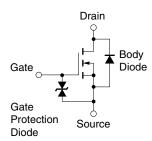


★ PACKAGE DRAWINGS (Unit: mm)





EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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